DGG OR DL PACKAGE (TOP VIEW)

SCDS008L - MAY 1993 - REVISED NOVEMBER 2001

- Member of the Texas Instruments Widebus™ Family
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

#### description

The SN74CBT16214 provides 12 bits of high-speed TTL-compatible bus switching between three separate ports. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device operates as a 12-bit bus-select switch via the data-select (S0–S2) terminals.

#### S0 56**∏** S1 1A 🛮 2 55 S2 1B3**∏**3 54 1 1B1 2A Π 4 53**∏**1B2 2B3 **∏** 5 52**∏**2B1 3A **∏** 6 51 1 2B2 3B3 **∏** 7 50**∏**3B1 GND **1**8 49 | GND 48**∏**3B2 4A 🗍 9 4B3 **∏** 10 47 **1** 4B1 46 1 4B2 5A 🛮 11 5B3 **∏** 12 45**∏**5B1 6A Π 13 44**∏**5B2 6B3 🛮 14 43 🛭 6B1 7A 🛮 15 42 6B2 7B3 **∏** 16 41**∏**7B1 40**∏**7B2 V<sub>CC</sub> **∐** 17 8A 🛮 18 39 8B1 GND **1** 19 38 | GND 37 8B2 8B3 **∏** 20 9A 🛮 21 36**∏**9B1 9B3 **1** 22 35**∏**9B2 10A 🛮 23 34 🛮 10B1 10B3 🛮 24 33 **1** 10B2 32**∏** 11B1 11A | 25 31 11B2 11B3 🛮 26 30 12B1 12A 🛮 27 12B3 [] 28 29 🛮 12B2

#### ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SSOP – DL	Tube	SN74CBT16214DL	CBT16214	
–40°C to 85°C	330F - DL	Tape and reel	SN74CBT16214DLR	CB110214	
	TSSOP – DGG	Tape and reel	SN74CBT16214DGGR	CBT16214	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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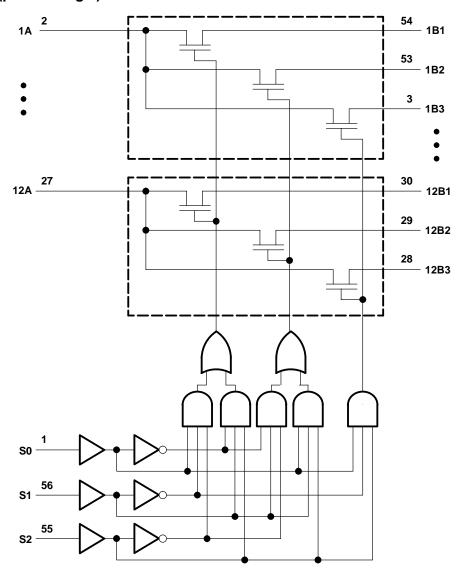


SCDS008L - MAY 1993 - REVISED NOVEMBER 2001

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	INPUTS		INPUT/OUTPUT	FUNCTION
S2	S1	S0	Α	FUNCTION
L	L	L	Z	Disconnect
L	L	Н	B1	A port = B1 port
L	Н	L	B2	A port = B2 port
L	Н	Н	Z	Disconnect
Н	L	L	Z	Disconnect
Н	L	Н	В3	A port = B3 port
Н	Н	L	B1	A port = B1 port
Н	Н	Н	B2	A port = B2 port

# logic diagram (positive logic)





SCDS008L - MAY 1993 - REVISED NOVEMBER 2001

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	$-0.5 \text{ V to 7 V}$
Input voltage range, V <sub>I</sub> (see Note 1)	$-0.5 \text{ V to 7 V}$
Continuous channel current	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	64°C
DL package	56°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2		V
VIL	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER		TEST CONDITIONS					UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA				-1.2	V
		$V_{CC} = 0$ ,	V <sub>I</sub> = 5.5 V				10	^
l II		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±1	μΑ
Icc		V <sub>C</sub> C = 5.5 V,	$I_{O} = 0$ ,	$V_I = V_{CC}$ or GND			3	μΑ
∆lcc§	Control inputs	V <sub>C</sub> C = 5.5 V,	One input at 3.4 V,	Other inputs at V <sub>CC</sub> or GND			2.5	mA
Ci	Control inputs	V <sub>I</sub> = 3 V or 0				4		pF
C <sub>io(OFF)</sub>		$V_{O} = 3 \text{ V or } 0,$	$S_0$ , $S_1$ , and $S_2 = G_1$	ND		7.5		pF
		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V <sub>I</sub> = 2.4 V,	I <sub>I</sub> = 15 mA		14	20	
ron¶			V. 0	I <sub>I</sub> = 64 mA		4	7	Ω
		V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 0	I <sub>I</sub> = 30 mA		4	7	
			V <sub>I</sub> = 2.4 V,	I <sub>I</sub> = 15 mA		6	12	

 $<sup>\</sup>ddagger$  All typical values are at  $V_{CC}$  = 5 V (unless otherwise noted),  $T_A$  = 25°C.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

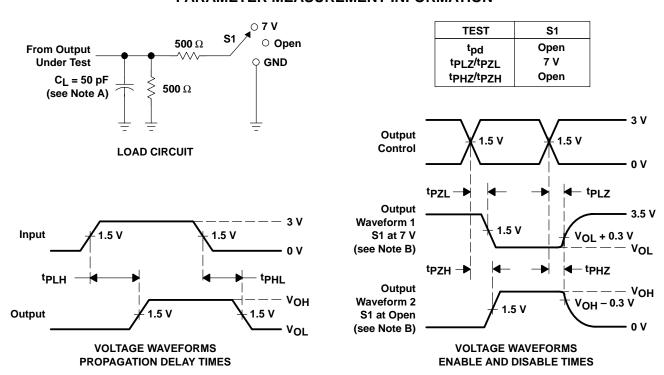
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## switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> =	4 V	V <sub>CC</sub> =	UNIT	
	(1141 01)	(0011 01)	MIN	MAX	MIN	MAX	
t <sub>pd</sub> †	A or B	B or A		0.35		0.25	ns
t <sub>pd</sub>	S	B or A		15.3	5.5	13.9	ns
t <sub>en</sub>	S	A or B		16	5.1	14.5	ns
t <sub>dis</sub>	S	A or B		12.1	3.6	11.7	ns

<sup>†</sup> The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

## PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns.  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74CBT16214DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBT16214DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16214DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



## \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16214DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74CBT16214DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT16214DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74CBT16214DLR	SSOP	DL	56	1000	346.0	346.0	49.0

## DL (R-PDSO-G\*\*)

## **48 PINS SHOWN**

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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